

## LM7341 Rail-to-Rail Input/Output $\pm 15V$ , 4.6 MHz GBW, Operational Amplifier in SOT-23 Package

Check for Samples: [LM7341](#)

### FEATURES

- ( $V_S = \pm 15V$ ,  $T_A = 25^\circ C$ , typical values.)
- Tiny 5-pin SOT-23 package saves space
- Greater than rail-to-rail input CMVR  $-15.3V$  to  $15.3V$
- Rail-to-rail output swing  $-14.84V$  to  $14.86V$
- Supply current 0.7 mA
- Gain bandwidth 4.6 MHz
- Slew Rate 1.9 V/ $\mu s$
- Wide supply range 2.7V to 32V
- High power supply rejection ratio 106 dB
- High common mode rejection ratio 115 dB
- Excellent gain 106 dB
- Temperature range  $-40^\circ C$  to  $125^\circ C$
- Tested at  $-40^\circ C$ ,  $125^\circ C$  and  $25^\circ C$  at 2.7V,  $\pm 5V$

and  $\pm 15V$ 

### APPLICATIONS

- Automotive
- Industrial robotics
- Sensor output buffers
- Multiple voltage power supplies
- Reverse biasing of photodiodes
- Low current optocouplers
- High side sensing
- Comparator
- Battery chargers
- Test point output buffers
- Below ground current sensing

### DESCRIPTION

The LM7341 is a rail-to-rail input and output amplifier in a small SOT-23 package with a wide supply voltage and temperature range. The LM7341 has a 4.6 MHz gain bandwidth and a 1.9 volt per microsecond slew rate, and draws 0.75 mA of supply current at no load.

The LM7341 is tested at  $-40^\circ C$ ,  $125^\circ C$  and  $25^\circ C$  with modern automatic test equipment. Detailed performance specifications at 2.7V,  $\pm 5V$ , and  $\pm 15V$  and over a wide temperature range make the LM7341 a good choice for automotive, industrial, and other demanding applications.

Greater than rail-to-rail input common mode range with a minimum 76 dB of common mode rejection at  $\pm 15V$  makes the LM7341 a good choice for both high and low side sensing applications.

LM7341 performance is consistent over a wide voltage range, making the part useful for applications where the supply voltage can change, such as automotive electrical systems and battery powered electronics.

The LM7341 uses a small SOT23-5 package, which takes up little board space, and can be placed near signal sources to reduce noise pickup.



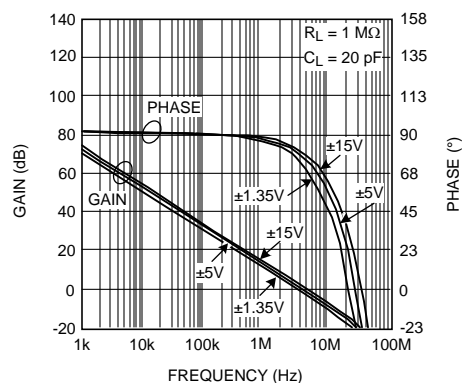
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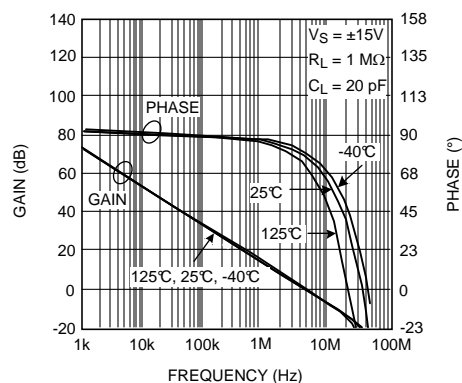
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## Typical Performance Characteristics



**Figure 1. Open Loop Frequency Response**



**Figure 2. Open Loop Frequency Response**



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## Absolute Maximum Ratings <sup>(1)</sup>

ESD Tolerance <sup>(2)</sup>	
Human Body Model	2000V
Machine Model	200V
Charge-Device Model	1000V
V <sub>IN</sub> Differential	±15V
Voltage at Input/Output Pin	(V <sup>+</sup> ) + 0.3V, (V <sup>-</sup> ) -0.3V
Supply Voltage (V <sub>S</sub> = V <sup>+</sup> - V <sup>-</sup> )	35V
Input Current	±10 mA
Output Current <sup>(3)</sup>	±20 mA
Power Supply Current	25 mA
Soldering Information	
Infrared or Convection (20 sec)	235°C
Wave Soldering Lead Temp. (10 sec.)	260°C
Storage Temperature Range	-65°C to 150°C
Junction Temperature <sup>(4)</sup>	150°C

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics.
- (2) Human Body Model, applicable std. MIL-STD-883, Method 3015.7. Machine Model, applicable std. JESD22-A115-A (ESD MM std. of JEDEC) Field-Induced Charge-Device Model, applicable std. JESD22-C101-C (ESD FICDM std. of JEDEC).
- (3) Applies to both single-supply and split-supply operation. Continuous short circuit operation at elevated ambient temperature can result in exceeding the maximum allowed junction temperature of 150°C.
- (4) The maximum power dissipation is a function of T<sub>J(MAX)</sub>, θ<sub>JA</sub>. The maximum allowable power dissipation at any ambient temperature is P<sub>D</sub> = (T<sub>J(MAX)</sub> - T<sub>A</sub>)/θ<sub>JA</sub>. All numbers apply for packages soldered directly unto a PC board.

## Operating Ratings <sup>(1)</sup>

Supply Voltage (V <sub>S</sub> = V <sup>+</sup> - V <sup>-</sup> )	2.5V to 32V
Temperature Range <sup>(2)</sup>	-40°C to 125°C
Package Thermal Resistance (θ <sub>JA</sub> )	
5-Pin SOT-23	325°C/W

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics.
- (2) The maximum power dissipation is a function of T<sub>J(MAX)</sub>, θ<sub>JA</sub>. The maximum allowable power dissipation at any ambient temperature is P<sub>D</sub> = (T<sub>J(MAX)</sub> - T<sub>A</sub>)/θ<sub>JA</sub>. All numbers apply for packages soldered directly unto a PC board.

## 2.7V Electrical Characteristics

Unless otherwise specified, all limits guaranteed for  $T_A = 25^\circ\text{C}$ ,  $V^+ = 2.7\text{V}$ ,  $V^- = 0\text{V}$ ,  $V_{\text{CM}} = 0.5\text{V}$ ,  $V_{\text{OUT}} = 1.35\text{V}$  and  $R_L > 1\text{M}\Omega$  to  $1.35\text{V}$ . **Boldface** limits apply at the temperature extremes

Symbol	Parameter	Conditions	Min (1)	Typ (2)	Max (1)	Units
$V_{\text{OS}}$	Input Offset Voltage	$V_{\text{CM}} = 0.5\text{V}$ and $V_{\text{CM}} = 2.2\text{V}$	-4 <b>-5</b>	$\pm 0.2$	+4 <b>+5</b>	mV
$\text{TCV}_{\text{OS}}$	Input Offset Voltage Temperature Drift			$\pm 2$		$\mu\text{V}/^\circ\text{C}$
$I_{\text{B}}$	Input Bias Current	$V_{\text{CM}} = 0.5\text{V}$	-180 <b>-200</b>	-90		nA
		$V_{\text{CM}} = 2.2\text{V}$		30	60 <b>70</b>	
$I_{\text{OS}}$	Input Offset Current	$V_{\text{CM}} = 0.5\text{V}$ and $V_{\text{CM}} = 2.2\text{V}$		1	40 <b>50</b>	nA
CMRR	Common Mode Rejection Ratio	$0\text{V} \leq V_{\text{CM}} \leq 1.0\text{V}$	82 <b>80</b>	106		dB
		$0\text{V} \leq V_{\text{CM}} \leq 2.7\text{V}$	62 <b>60</b>	80		
PSRR	Power Supply Rejection Ratio	$2.7\text{V} \leq V_{\text{S}} \leq 30\text{V}$ $V_{\text{CM}} = 0.5\text{V}$	86 <b>84</b>	106		dB
CMVR	Common Mode Voltage Range	CMRR > 60 dB		-0.3	<b>0.0</b>	V
			<b>2.7</b>	3.0		
$A_{\text{VOL}}$	Open Loop Voltage Gain	$0.5\text{V} \leq V_{\text{O}} \leq 2.2\text{V}$ $R_L = 10\text{ k}\Omega$ to $1.35\text{V}$	12 <b>8</b>	65		V/mV
$V_{\text{OUT}}$	Output Voltage Swing High	$R_L = 10\text{ k}\Omega$ to $1.35\text{V}$ $V_{\text{ID}} = 100\text{ mV}$		50	120 <b>150</b>	mV from either rail
		$R_L = 2\text{ k}\Omega$ to $1.35\text{V}$ $V_{\text{ID}} = 100\text{ mV}$		95	150 <b>200</b>	
	Output Voltage Swing Low	$R_L = 10\text{ k}\Omega$ to $1.35\text{V}$ $V_{\text{ID}} = -100\text{ mV}$		55	120 <b>150</b>	
		$R_L = 2\text{ k}\Omega$ to $1.35\text{V}$ $V_{\text{ID}} = -100\text{ mV}$		100	150 <b>200</b>	
$I_{\text{OUT}}$	Output Current	Sourcing, $V_{\text{OUT}} = 0\text{V}$ $V_{\text{ID}} = 200\text{ mV}$	6 <b>4</b>	12		mA
		Sinking, $V_{\text{OUT}} = 0\text{V}$ $V_{\text{ID}} = -200\text{ mV}$	5 <b>3</b>	10		
$I_{\text{S}}$	Supply Current	$V_{\text{CM}} = 0.5\text{V}$ and $V_{\text{CM}} = 2.2\text{V}$		0.6	0.9 <b>1.0</b>	mA
SR	Slew Rate	$\pm 1\text{V}$ Step		1.5		V/ $\mu\text{s}$
GBW	Gain Bandwidth	$f = 100\text{ kHz}$ , $R_L = 100\text{ k}\Omega$		3.6		MHz
$e_{\text{n}}$	Input Referred Voltage Noise Density	$f = 1\text{ kHz}$		35		$\text{nV}/\sqrt{\text{Hz}}$
$i_{\text{n}}$	Input Referred Voltage Noise Density	$f = 1\text{ kHz}$		0.28		$\text{pA}/\sqrt{\text{Hz}}$
THD+N	Total Harmonic Distortion + Noise	$f = 10\text{ kHz}$		-66		dB
$t_{\text{PD}}$	Propagation Delay	Overdrive = 50 mV <sup>(3)</sup>		4		$\mu\text{s}$
		Overdrive = 1V <sup>(3)</sup>		3		
$t_{\text{r}}$	Rise Time	20% to 80% <sup>(3)</sup>		1		$\mu\text{s}$
$t_{\text{f}}$	Fall Time	80% to 20% <sup>(3)</sup>		1		$\mu\text{s}$

(1) All limits are guaranteed by testing or statistical analysis.

(2) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not guaranteed on shipped production material.

(3) The maximum differential voltage between the input pins is  $V_{\text{IN Differential}} = \pm 15\text{V}$ .

## ±5V Electrical Characteristics

Unless otherwise specified, all limits guaranteed for  $T_A = 25^\circ\text{C}$ ,  $V^+ = +5\text{V}$ ,  $V^- = -5\text{V}$ ,  $V_{CM} = V_{OUT} = 0\text{V}$  and  $R_L > 1\text{ M}\Omega$  to  $0\text{V}$ . **Boldface** limits apply at the temperature extremes.

Symbol	Parameter	Conditions	Min (1)	Typ (2)	Max (1)	Units
$V_{OS}$	Input Offset Voltage	$V_{CM} = -4.5\text{V}$ and $V_{CM} = 4.5\text{V}$	-4 <b>-5</b>	$\pm 0.2$	+4 <b>+5</b>	mV
$TCV_{OS}$	Input Offset Voltage Temperature Drift			$\pm 2$		$\mu\text{V}/^\circ\text{C}$
$I_B$	Input Bias Current	$V_{CM} = -4.5\text{V}$	-200 <b>-250</b>	-95		nA
		$V_{CM} = 4.5\text{V}$		35	70 <b>80</b>	
$I_{OS}$	Input Offset Current	$V_{CM} = -4.5\text{V}$ and $V_{CM} = 4.5\text{V}$		1	40 <b>50</b>	nA
CMRR	Common Mode Rejection Ratio	$-5\text{V} \leq V_{CM} \leq 3\text{V}$	84 <b>82</b>	112		dB
		$-5\text{V} \leq V_{CM} \leq 5\text{V}$	72 <b>70</b>	92		
PSRR	Power Supply Rejection Ratio	$2.7\text{V} \leq V_S \leq 30\text{V}$ , $V_{CM} = -4.5\text{V}$	86 <b>84</b>	106		dB
CMVR	Common Mode Voltage Range	CMRR $\geq 65\text{ dB}$		-5.3	<b>-5.0</b>	V
			<b>5.0</b>	5.3		
$A_{VOL}$	Open Loop Voltage Gain	$-4\text{V} \leq V_O \leq 4\text{V}$ $R_L = 10\text{ k}\Omega$ to $0\text{V}$	20 <b>12</b>	110		V/mV
$V_{OUT}$	Output Voltage Swing High	$R_L = 10\text{ k}\Omega$ to $0\text{V}$ , $V_{ID} = 100\text{ mV}$		80	150 <b>200</b>	mV from either rail
		$R_L = 2\text{ k}\Omega$ to $0\text{V}$ , $V_{ID} = 100\text{ mV}$		170	300 <b>400</b>	
	Output Voltage Swing Low	$R_L = 10\text{ k}\Omega$ to $0\text{V}$ , $V_{ID} = -100\text{ mV}$		90	150 <b>200</b>	
		$R_L = 2\text{ k}\Omega$ to $0\text{V}$ , $V_{ID} = -100\text{ mV}$		210	300 <b>400</b>	
$I_{OUT}$	Output Current	Sourcing, $V_{OUT} = -5\text{V}$ $V_{ID} = 200\text{ mV}$	6 <b>4</b>	11		mA
		Sinking, $V_{OUT} = 5\text{V}$ $V_{ID} = -200\text{ mV}$	6 <b>4</b>	12		
$I_S$	Supply Current	$V_{CM} = -4.5\text{V}$ and $V_{CM} = 4.5\text{V}$		0.65	1.0 <b>1.1</b>	mA
SR	Slew Rate	$\pm 4\text{V}$ Step		1.7		V/ $\mu\text{s}$
GBW	Gain Bandwidth	$f = 100\text{ kHz}$ , $R_L = 100\text{ k}\Omega$		4.0		MHz
$e_n$	Input Referred Voltage Noise Density	$f = 1\text{ kHz}$		33		$\text{nV}/\sqrt{\text{Hz}}$
$i_n$	Input Referred Voltage Noise Density	$f = 1\text{ kHz}$		0.26		$\text{pA}/\sqrt{\text{Hz}}$
THD+N	Total Harmonic Distortion + Noise	$f = 10\text{ kHz}$		-66		dB
$t_{PD}$	Propagation Delay	Overdrive = $50\text{ mV}$ <sup>(3)</sup>		8		$\mu\text{s}$
		Overdrive = $1\text{ V}$ <sup>(3)</sup>		6		
$t_r$	Rise Time	20% to 80% <sup>(3)</sup>		5		$\mu\text{s}$
$t_f$	Fall Time	80% to 20% <sup>(3)</sup>		5		$\mu\text{s}$

(1) All limits are guaranteed by testing or statistical analysis.

(2) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not guaranteed on shipped production material.

(3) The maximum differential voltage between the input pins is  $V_{IN\text{ Differential}} = \pm 15\text{V}$ .

## ±15V Electrical Characteristics

Unless otherwise specified, all limits guaranteed for  $T_A = 25^\circ\text{C}$ ,  $V^+ = 15\text{V}$ ,  $V^- = -15\text{V}$ ,  $V_{\text{CM}} = V_{\text{OUT}} = 0\text{V}$  and  $R_L > 1\text{ M}\Omega$  to  $0\text{V}$ . **Boldface** limits apply at the temperature extremes

Symbol	Parameter	Conditions	Min (1)	Typ (2)	Max (1)	Units
$V_{\text{OS}}$	Input Offset Voltage	$V_{\text{CM}} = -14.5\text{V}$ and $V_{\text{CM}} = 14.5\text{V}$	-4 <b>-5</b>	$\pm 0.2$	+4 <b>+5</b>	mV
$\text{TCV}_{\text{OS}}$	Input Offset Voltage Temperature Drift			$\pm 2$		$\mu\text{V}/^\circ\text{C}$
$I_{\text{B}}$	Input Bias Current	$V_{\text{CM}} = -14.5\text{V}$	-250 <b>-300</b>	-110		nA
		$V_{\text{CM}} = 14.5\text{V}$		40	80 <b>90</b>	
$I_{\text{OS}}$	Input Offset Current	$V_{\text{CM}} = -14.5\text{V}$ and $V_{\text{CM}} = 14.5\text{V}$		1	40 <b>50</b>	nA
CMRR	Common Mode Rejection Ratio	$-15\text{V} \leq V_{\text{CM}} \leq 12\text{V}$	84 <b>82</b>	115		dB
		$-15\text{V} \leq V_{\text{CM}} \leq 15\text{V}$	78 <b>76</b>	100		
PSRR	Power Supply Rejection Ratio	$2.7\text{V} \leq V_{\text{S}} \leq 30\text{V}$ , $V_{\text{CM}} = -14.5\text{V}$	86 <b>84</b>	106		dB
CMVR	Common Mode Voltage Range	CMRR > 80 dB		-15.3	<b>-15.0</b>	V
			<b>15.0</b>	15.3		
$A_{\text{VOL}}$	Open Loop Voltage Gain	$-13\text{V} \leq V_{\text{O}} \leq 13\text{V}$ $R_L = 10\text{ k}\Omega$ to $0\text{V}$	25 <b>15</b>	200		V/mV
$V_{\text{OUT}}$	Output Voltage Swing High	$R_L = 10\text{ k}\Omega$ to $0\text{V}$ $V_{\text{ID}} = 100\text{ mV}$		135	300 <b>400</b>	mV from either rail
	Output Voltage Swing Low	$R_L = 10\text{ k}\Omega$ to $0\text{V}$ $V_{\text{ID}} = -100\text{ mV}$		160	300 <b>400</b>	
$I_{\text{OUT}}$	Output Current (3)	Sourcing, $V_{\text{OUT}} = -15\text{V}$ $V_{\text{ID}} = 200\text{ mV}$	5 <b>3</b>	10		mA
		Sinking, $V_{\text{OUT}} = 15\text{V}$ $V_{\text{ID}} = -200\text{ mV}$	8 <b>5</b>	13		
$I_{\text{S}}$	Supply Current	$V_{\text{CM}} = -14.5\text{V}$ and $V_{\text{CM}} = 14.5\text{V}$		0.7	1.2 <b>1.3</b>	mA
SR	Slew Rate	$\pm 12\text{V}$ Step		1.9		V/ $\mu\text{s}$
GBW	Gain Bandwidth	$f = 100\text{ kHz}$ , $R_L = 100\text{ k}\Omega$		4.6		MHz
$e_n$	Input Referred Voltage Noise Density	$f = 1\text{ kHz}$		31		$\text{nV}/\sqrt{\text{Hz}}$
$i_n$	Input Referred Current Noise Density	$f = 1\text{ kHz}$		0.27		$\text{pA}/\sqrt{\text{Hz}}$
THD+N	Total Harmonic Distortion + Noise	$f = 10\text{ kHz}$		-65		dB
$t_{\text{PD}}$	Propagation Delay	Overdrive = 50 mV (4)		17		$\mu\text{s}$
		Overdrive = 1V (4)		12		
$t_r$	Rise Time	20% to 80% (4)		13		$\mu\text{s}$
$t_f$	Fall Time	80% to 20% (4)		13		$\mu\text{s}$

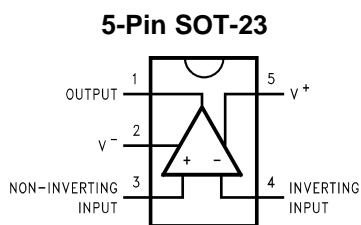
(1) All limits are guaranteed by testing or statistical analysis.

(2) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not guaranteed on shipped production material.

(3) The maximum power dissipation is a function of  $T_{\text{J(MAX)}}$ ,  $\theta_{\text{JA}}$ . The maximum allowable power dissipation at any ambient temperature is  $P_{\text{D}} = (T_{\text{J(MAX)}} - T_{\text{A}})/\theta_{\text{JA}}$ . All numbers apply for packages soldered directly unto a PC board.

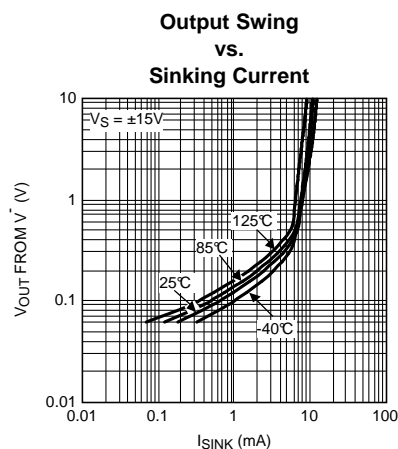
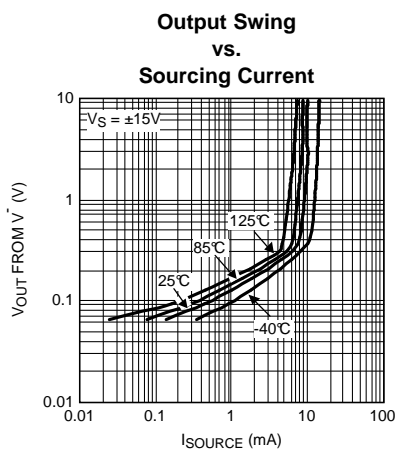
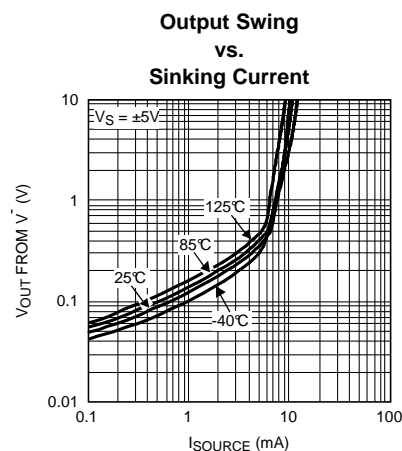
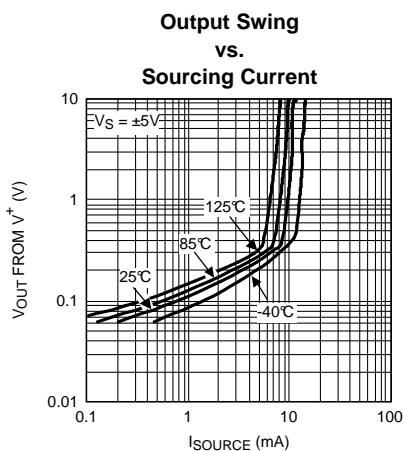
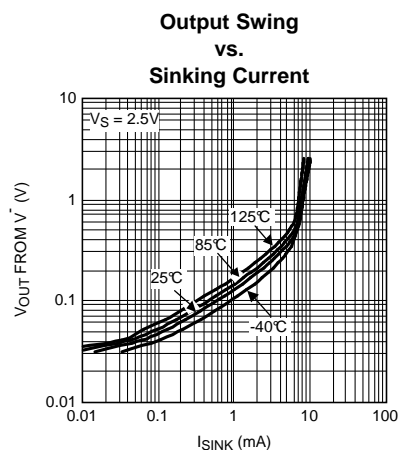
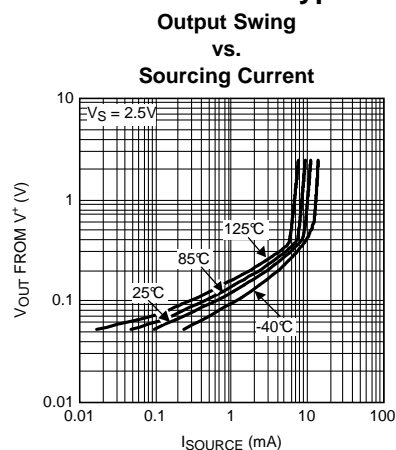
(4) The maximum differential voltage between the input pins is  $V_{\text{IN Differential}} = \pm 15\text{V}$ .

## Connection Diagram



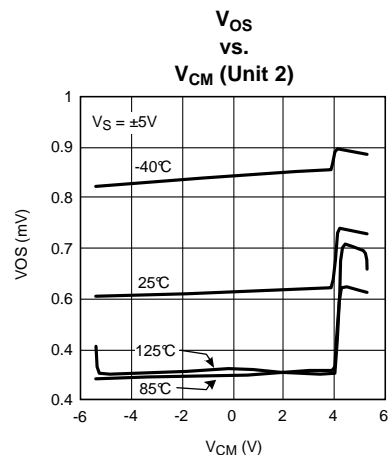
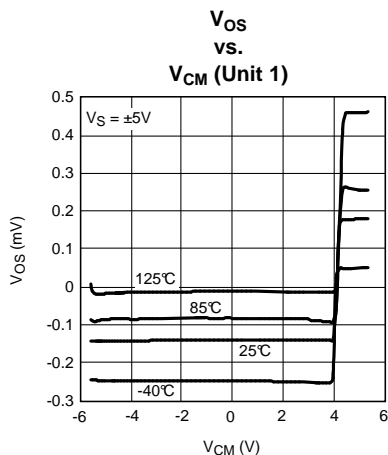
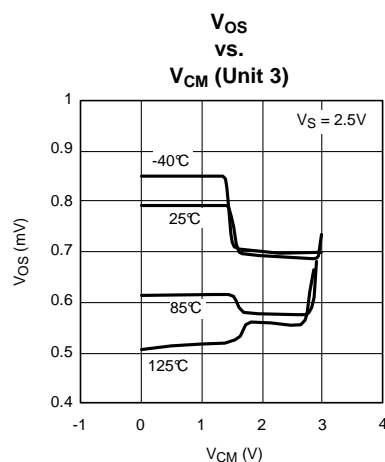
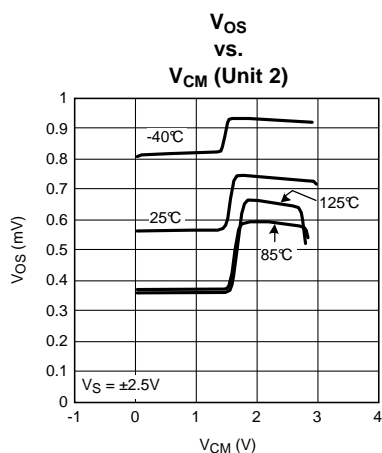
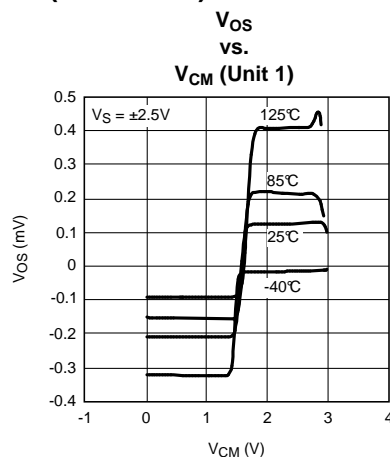
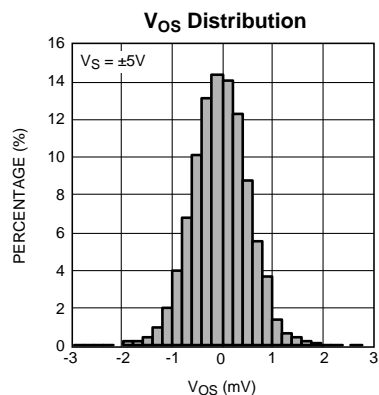
**Figure 3. Top View**

## Typical Performance Characteristics

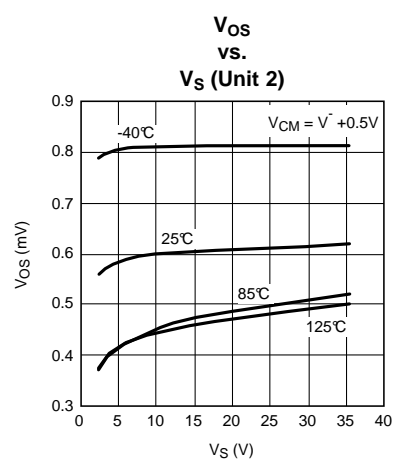
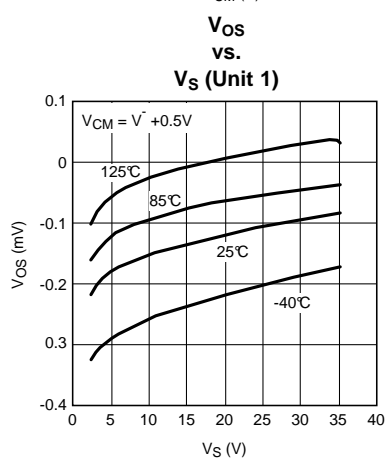
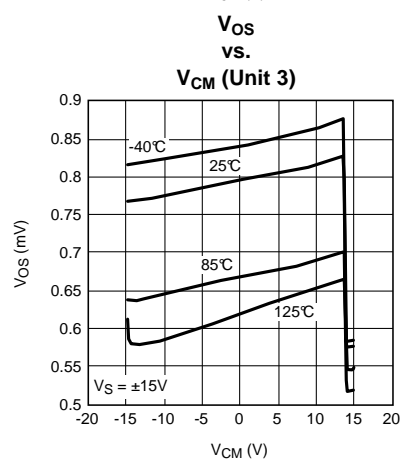
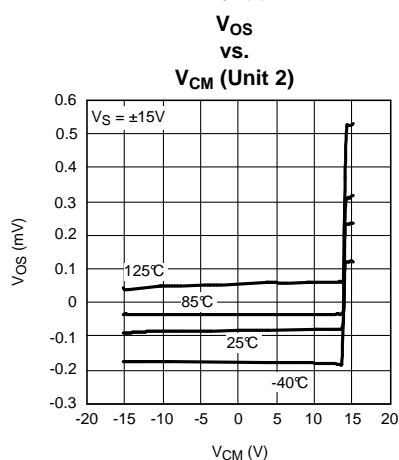
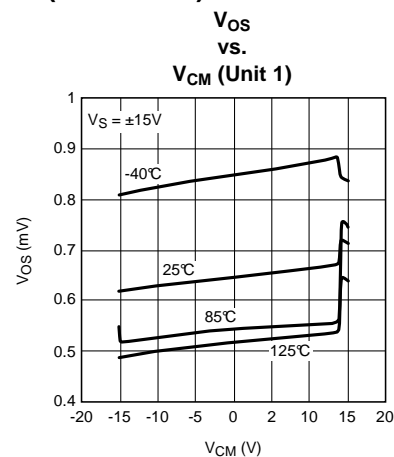
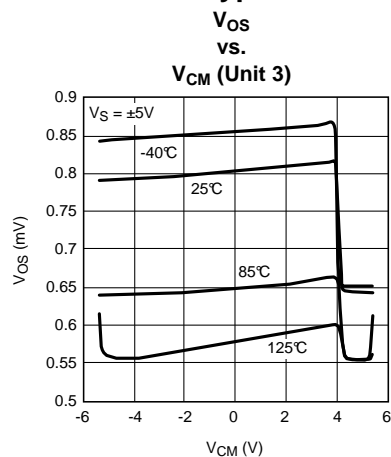




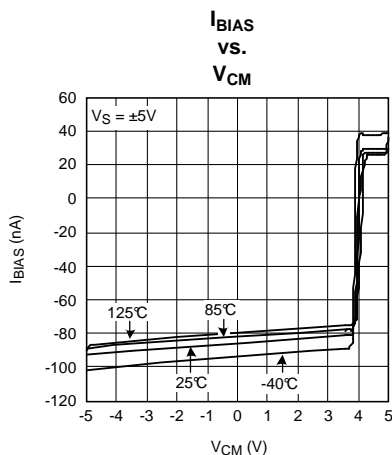
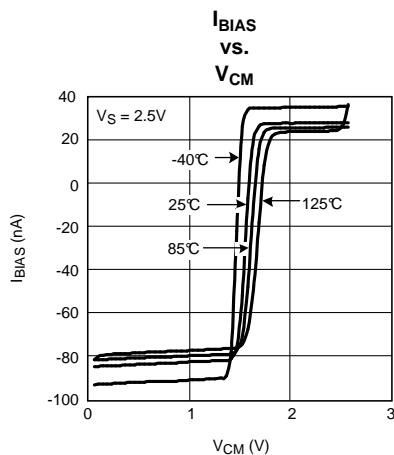
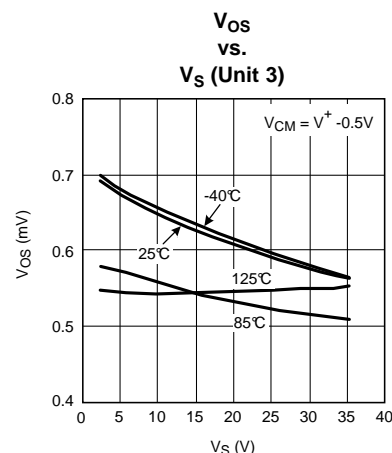
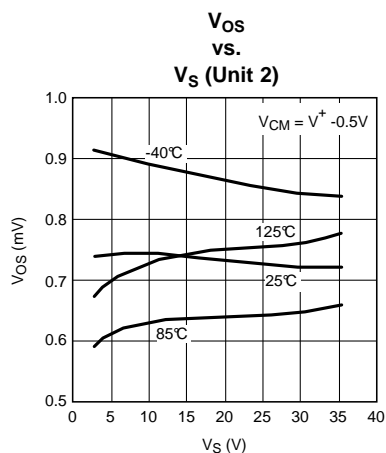
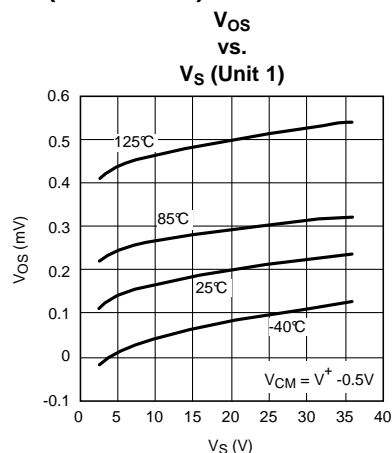
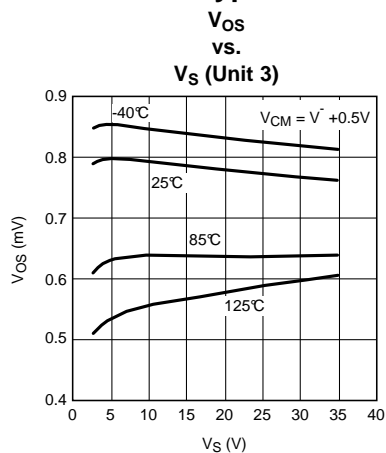
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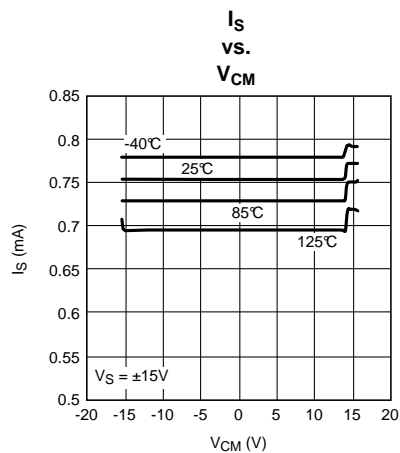
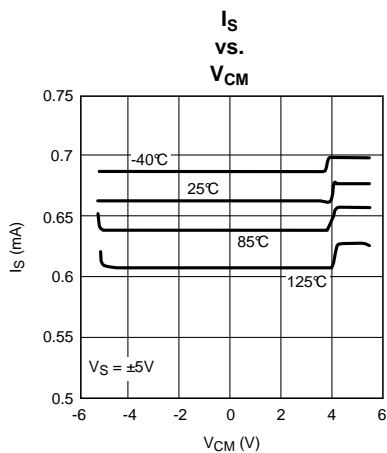
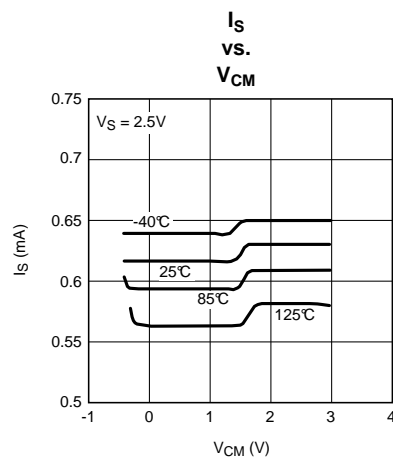
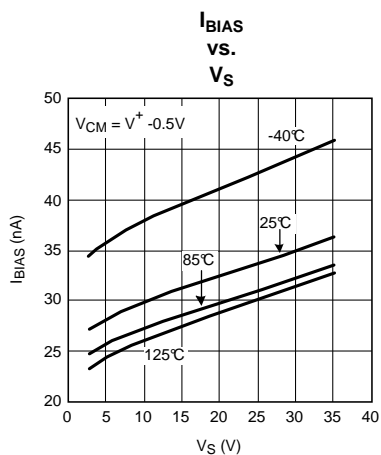
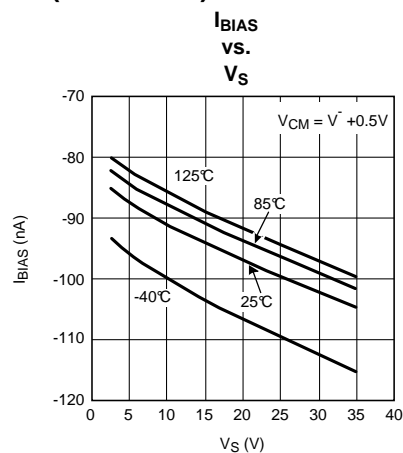
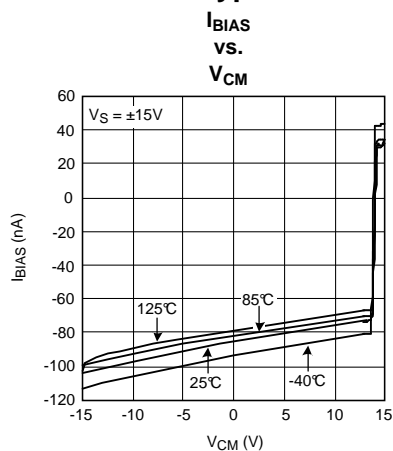
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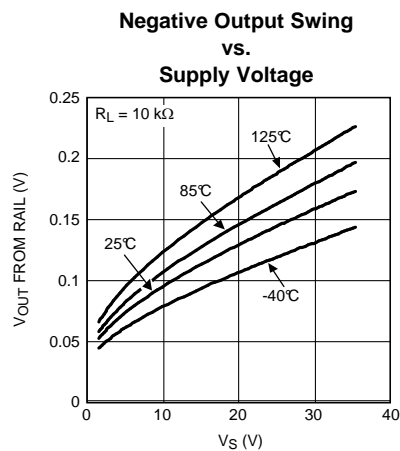
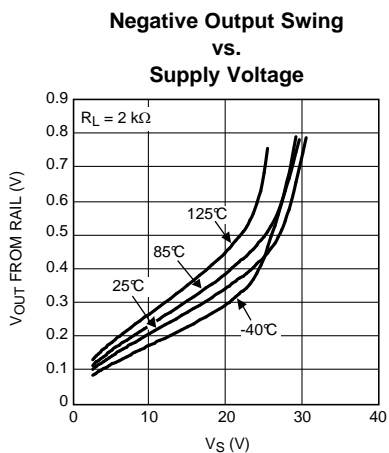
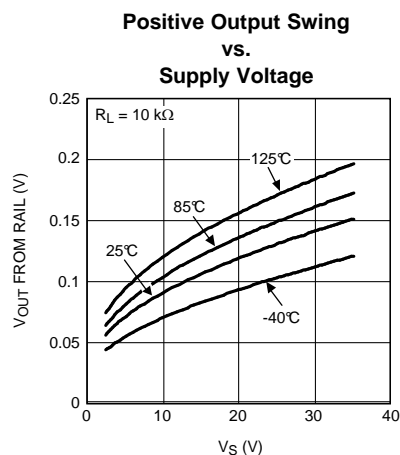
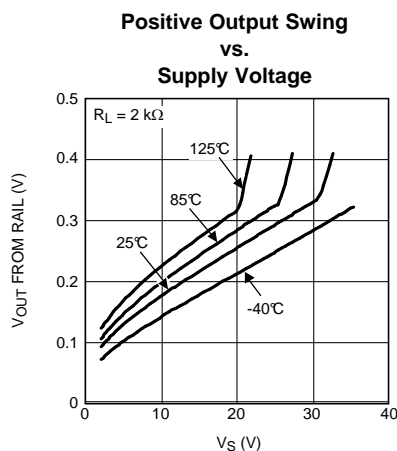
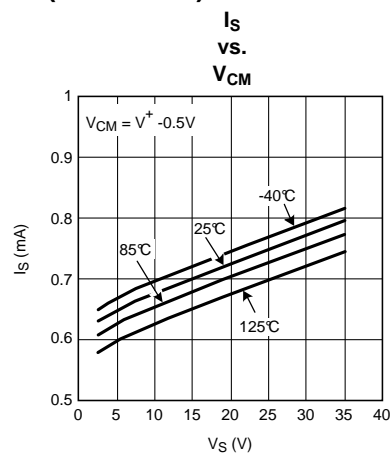
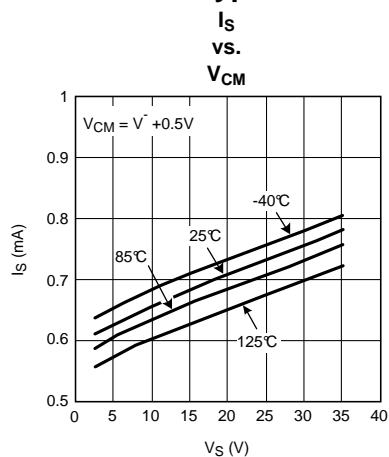
## Typical Performance Characteristics (continued)



## Typical Performance Characteristics (continued)

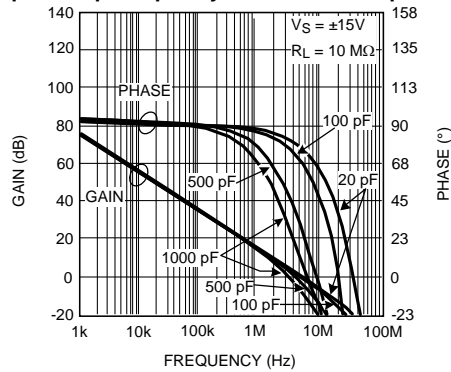


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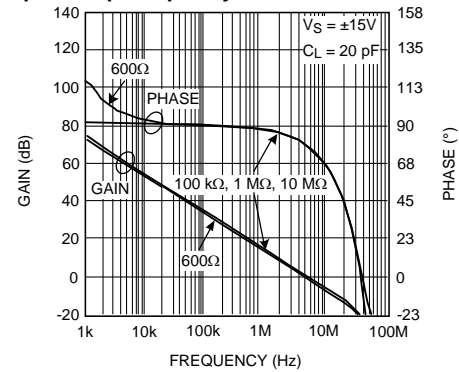


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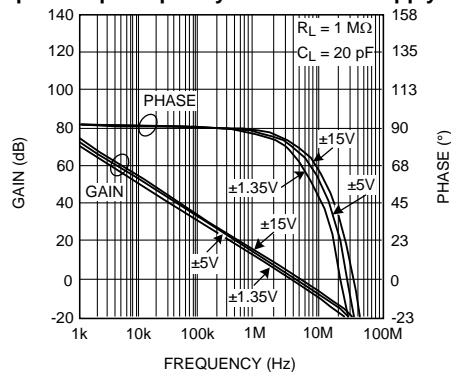
### Open Loop Frequency with Various Capacitive Load



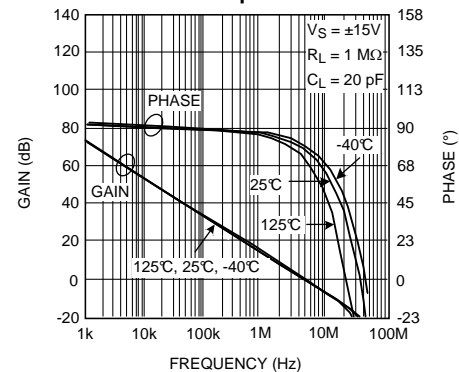
### Open Loop Frequency with Various Resistive Load



### Open Loop Frequency with Various Supply Voltage



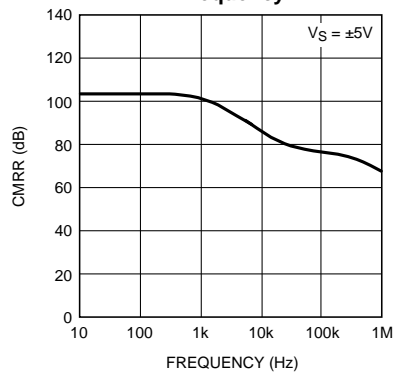
### Open Loop Frequency Response with Various Temperatures



CMRR

vs.

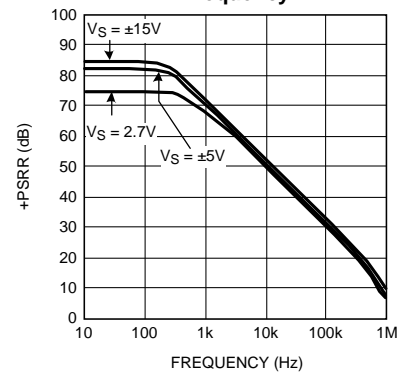
Frequency



+PSRR

vs.

Frequency

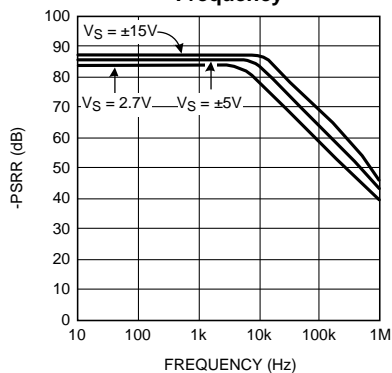


## Typical Performance Characteristics (continued)

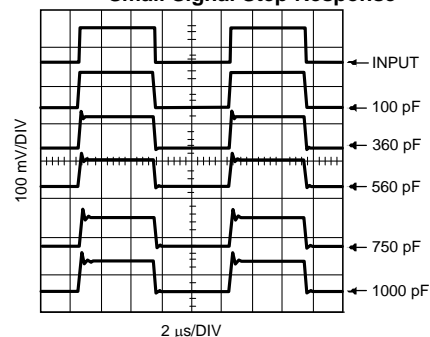
-PSRR

vs.

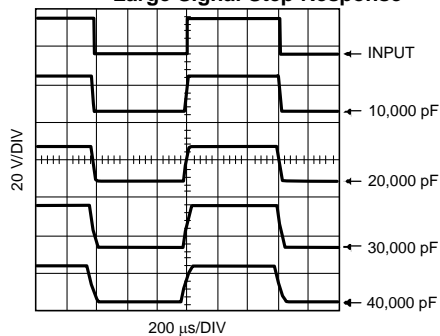
Frequency



Small Signal Step Response



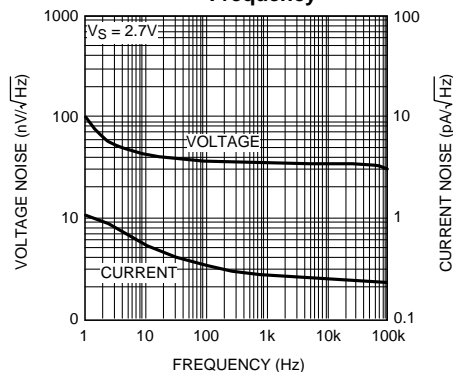
Large Signal Step Response



Input Referred Noise Density

vs.

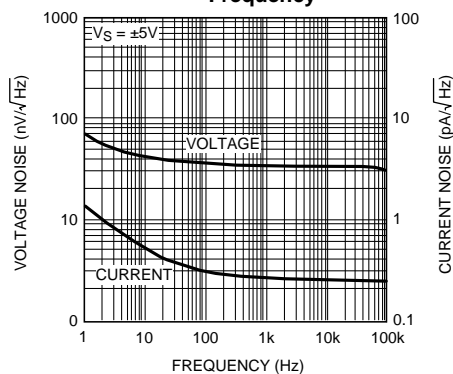
Frequency



Input Referred Noise Density

vs.

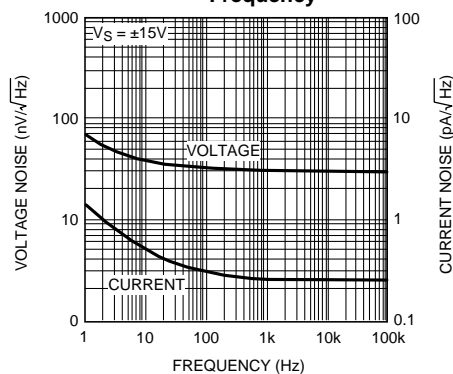
Frequency



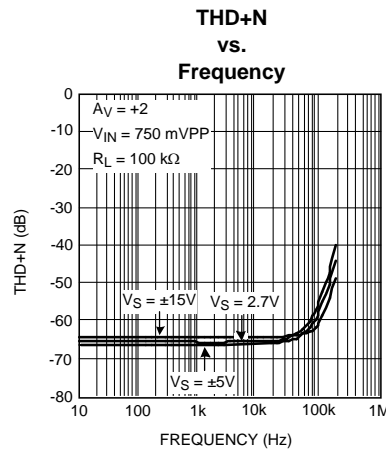
Input Referred Noise Density

vs.

Frequency



## Typical Performance Characteristics (continued)



## Application Information

### GENERAL INFORMATION

Low supply current and wide bandwidth, greater than rail-to-rail input range, full rail-to-rail output, good capacitive load driving ability, wide supply voltage and low distortion all make the LM7341 ideal for many diverse applications.

The high common-mode rejection ratio and full rail-to-rail input range provides precision performance when operated in non-inverting applications where the common-mode error is added directly to the other system errors.

### CAPACITIVE LOAD DRIVING

The LM7341 has the ability to drive large capacitive loads. For example, 1000 pF only reduces the phase margin to about 30 degrees.

### POWER DISSIPATION

Although the LM7341 has internal output current limiting, shorting the output to ground when operating on a +30V power supply will cause the op amp to dissipate about 350 mW. This is a worst-case example. In the 5-pin SOT-23 package, the higher thermal resistance will cause a calculated rise of 113°C. This can raise the junction temperature to above the absolute maximum temperature of 150°C.

Operating from split supplies greatly reduces the power dissipated when the output is shorted. Operating on ±15V supplies can only cause a temperature rise of 57°C in the 5-pin SOT-23 package, assuming the short is to ground.

### WIDE SUPPLY RANGE

The high power-supply rejection ratio (PSRR) and common mode rejection ratio (CMRR) provide precision performance when operated on battery or other unregulated supplies. This advantage is further enhanced by the very wide supply range (2.5V–32V) offered by the LM7341. In situations where highly variable or unregulated supplies are present, the excellent PSRR and wide supply range of the LM7341 benefit the system designer with continued precision performance, even in such adverse supply conditions.

### SPECIFIC ADVANTAGES OF 5-Pin SOT-23 (TinyPak)

The obvious advantage of the 5-pin SOT-23, TinyPak, is that it can save board space, a critical aspect of any portable or miniaturized system design. The need to decrease overall system size is inherent in any handheld, portable, or lightweight system application.

Furthermore, the low profile can help in height limited designs, such as consumer hand-held remote controls, sub-notebook computers, and PCMCIA cards.



An additional advantage of the tiny package is that it allows better system performance due to ease of package placement. Because the tiny package is so small, it can fit on the board right where the op amp needs to be placed for optimal performance, unconstrained by the usual space limitations. This optimal placement of the tiny package allows for many system enhancements, not easily achieved with the constraints of a larger package. For example, problems such as system noise due to undesired pickup of digital signals can be easily reduced or mitigated. This pick-up problem is often caused by long wires in the board layout going to or from an op amp. By placing the tiny package closer to the signal source and allowing the LM7341 output to drive the long wire, the signal becomes less sensitive to such pick-up. An overall reduction of system noise results.

Often times system designers try to save space by using dual or quad op amps in their board layouts. This causes a complicated board layout due to the requirement of routing several signals to and from the same place on the board. Using the tiny op amp eliminates this problem.

Additional space savings parts are available in tiny packages from National Semiconductor, including low power amplifiers, precision voltage references, and voltage regulators.

### **LOW DISTORTION, HIGH OUTPUT DRIVE CAPABILITY**

The LM7341 offers superior low-distortion performance, with a total-harmonic-distortion-plus-noise of  $-66$  dB at  $f = 10$  kHz. The advantage offered by the LM7341 is its low distortion levels, even at high output current and low load resistance.

### **Typical Applications**

#### **HANDHELD REMOTE CONTROLS**

The LM7341 offers outstanding specifications for applications requiring good speed/power trade-off. In applications such as remote control operation, where high bandwidth and low power consumption are needed. The LM7341 performance can easily meet these requirements.

#### **OPTICAL LINE ISOLATION FOR MODEMS**

The combination of the low distortion and good load driving capabilities of the LM7341 make it an excellent choice for driving opto-coupler circuits to achieve line isolation for modems. This technique prevents telephone line noise from coupling onto the modem signal. Superior isolation is achieved by coupling the signal optically from the computer modem to the telephone lines; however, this also requires a low distortion at relatively high currents. Due to its low distortion at high output drive currents, the LM7341 fulfills this need, in this and in other telecom applications.

#### **REMOTE MICROPHONE IN PERSONAL COMPUTERS**

Remote microphones in Personal Computers often utilize a microphone at the top of the monitor which must drive a long cable in a high noise environment. One method often used to reduce the noise is to lower the signal impedance, which reduces the noise pickup. In this configuration, the amplifier usually requires 30 dB–40 dB of gain, at bandwidths higher than most low-power CMOS parts can achieve. The LM7341 offers the tiny package, higher bandwidths, and greater output drive capability than other rail-to-rail input/output parts can provide for this application.

#### **LM7341 AS A COMPARATOR**

The LM7341 can also be used as a comparator and provides quite reasonable performance. Note however that unlike a typical comparator an op amp has a maximum allowed differential voltage between the input pins. For the LM7341, as stated in the Absolute Maximum Ratings section, this maximum voltage is  $V_{IN\ Differential} = \pm 15V$ . Beyond this limit, even for a short time, damage to the device may occur.

As an inverting comparator at  $V_S = 30V$  and 1V of overdrive there is typically 12  $\mu s$  of propagation delay. At  $V_S = 30V$  and 50 mV of overdrive there is typically 17  $\mu s$  of propagation delay.

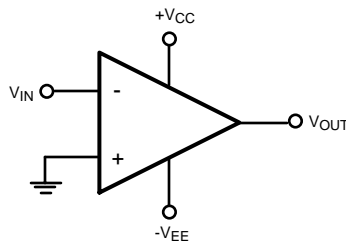


Figure 4. Inverting Comparator

Similarly a non-inverting comparator at  $V_S = 30V$  and 1V of overdrive there is typically 12  $\mu s$  of propagation delay. At  $V_S = 30V$  and 50 mV of overdrive there is typically 17  $\mu s$  of propagation delay.

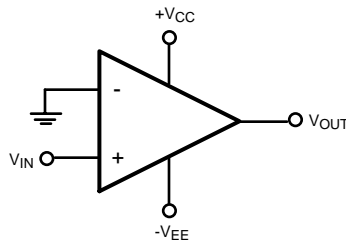


Figure 5. Non-Inverting Comparator

## COMPARATOR WITH HYSTERESIS

The basic comparator configuration may oscillate or produce a noisy output if the applied differential input voltage is near the comparator's offset voltage. This usually happens when the input signal is moving very slowly across the comparator's switching threshold. This problem can be prevented by the addition of hysteresis or positive feedback.

### INVERTING COMPARATOR WITH HYSTERESIS

The inverting comparator with hysteresis requires a three resistor network that is referenced to the supply voltage  $V_{CC}$  of the comparator, as shown in Figure 6. When  $V_{IN}$  at the inverting input is less than  $V_A$ , the voltage at the non-inverting node of the comparator ( $V_{IN} < V_A$ ), the output voltage is high (for simplicity assume  $V_{OUT}$  switches as high as  $V_{CC}$ ). The three network resistors can be represented as  $R_1 || R_3$  in series with  $R_2$ . The lower input trip voltage  $V_{A1}$  is defined as

$$V_{A1} = V_{CC} R_2 / ((R_1 || R_3) + R_2) \quad (1)$$

When  $V_{IN}$  is greater than  $V_A$  ( $V_{IN} > V_A$ ), the output voltage is low, very close to ground. In this case the three network resistors can be presented as  $R_2 || R_3$  in series with  $R_1$ . The upper trip voltage  $V_{A2}$  is defined as

$$V_{A2} = V_{CC} (R_2 || R_3) / ((R_1 + (R_2 || R_3))) \quad (2)$$

The total hysteresis provided by the network is defined as

$$\Delta V_A = V_{A1} - V_{A2} \quad (3)$$

For example to achieve 50 mV of hysteresis when  $V_{CC} = 30V$  set  $R_1 = 4.02 \text{ k}\Omega$ ,  $R_2 = 4.02 \text{ k}\Omega$ , and  $R_3 = 1.21 \text{ M}\Omega$ . With these resistors selected the error due to input bias current is approximately 1 mV. To minimize this error it is best to use low resistor values on the inputs.

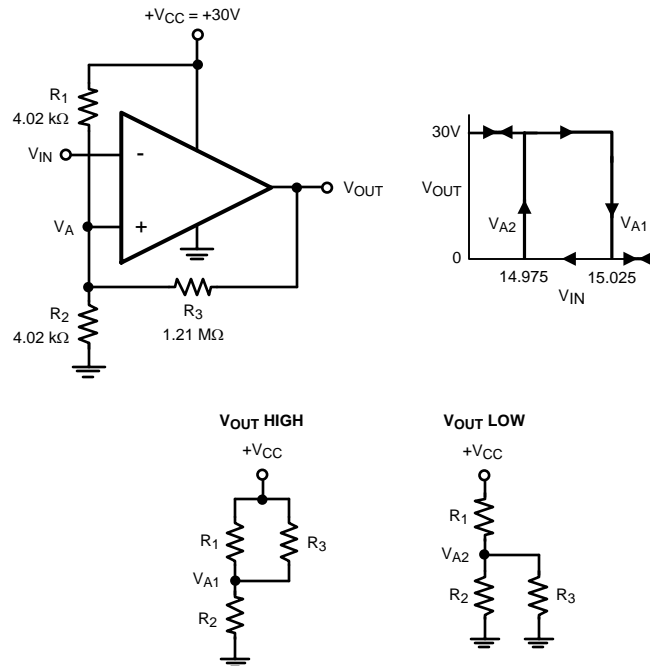


Figure 6. Inverting Comparator with Hysteresis

### NON-INVERTING COMPARATOR WITH HYSTERESIS

A non-inverting comparator with hysteresis requires a two resistor network, and a voltage reference ( $V_{REF}$ ) at the inverting input. When  $V_{IN}$  is low, the output is also low. For the output to switch from low to high,  $V_{IN}$  must rise up to  $V_{IN1}$  where  $V_{IN1}$  is calculated by

$$V_{IN1} = R_1 * (V_{REF}/R_2) + V_{REF} \quad (4)$$

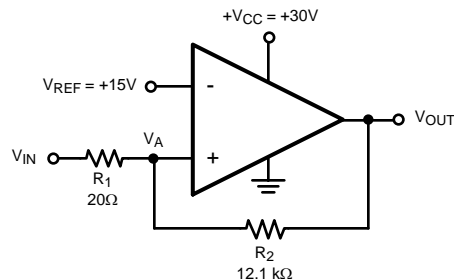
When  $V_{IN}$  is high, the output is also high, to make the comparator switch back to it's low state,  $V_{IN}$  must equal  $V_{REF}$  before  $V_A$  will again equal  $V_{REF}$ .  $V_{IN}$  can be calculated by

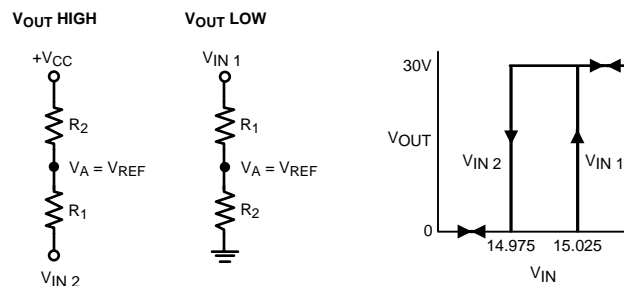
$$V_{IN2} = (V_{REF} (R_1 + R_2) - V_{CC}R_1)/R_2 \quad (5)$$

The hysteresis of this circuit is the difference between  $V_{IN1}$  and  $V_{IN2}$ .

$$\Delta V_{IN} = V_{CC}R_1/R_2 \quad (6)$$

For example to achieve 50 mV of hysteresis when  $V_{CC} = 30V$  set  $R_1 = 20\Omega$  and  $R_2 = 12.1 k\Omega$ .





**Figure 7. Non-Inverting Comparator with Hysteresis**

### OTHER SOT-23 AMPLIFIERS

The **LM7321** is a rail-to-rail input and output amplifier that can tolerate unlimited capacitive load. It works from 2.7V to  $\pm 15$ V and across the  $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$  temperature range. It has 20 MHz gain-bandwidth, and is available in both 5-Pin SOT-23 and 8-Pin SOIC packages.

The **LM6211** is a 20 MHz part with CMOS input, which runs on 5V to 24V single supplies. It has rail-to-rail output and low noise.

The **LMP7701** is a rail-to-rail input and output precision part with an input voltage offset under 220 microvolts and low noise. It has 2.5 MHz bandwidth and works on 2.7V to 12V supplies.

### SMALLER SC70 AMPLIFIERS

The **LMV641** is a 10 MHz amplifier which uses only 140 micro amps of supply current. The input voltage offset is less than 0.5 mV.

The **LMV851** is an 8 MHz amplifier which uses only 0.4 mA supply current, and is available in the smaller SC70 package. The LMV851 also resists Electro Magnetic Interference (EMI) from mobile phones and similar high frequency sources. It works on 2.7V to 5.5 V supplies.

Detailed information on these and a wide range of other parts can be found at [www.national.com](http://www.national.com).

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM7341MF/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	AV4A	<a href="#">Samples</a>
LM7341MFE/NOPB	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	AV4A	<a href="#">Samples</a>
LM7341MFX/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	AV4A	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM7341MF/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LM7341MFE/NOPB	SOT-23	DBV	5	250	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LM7341MFX/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

## TAPE AND REEL BOX DIMENSIONS

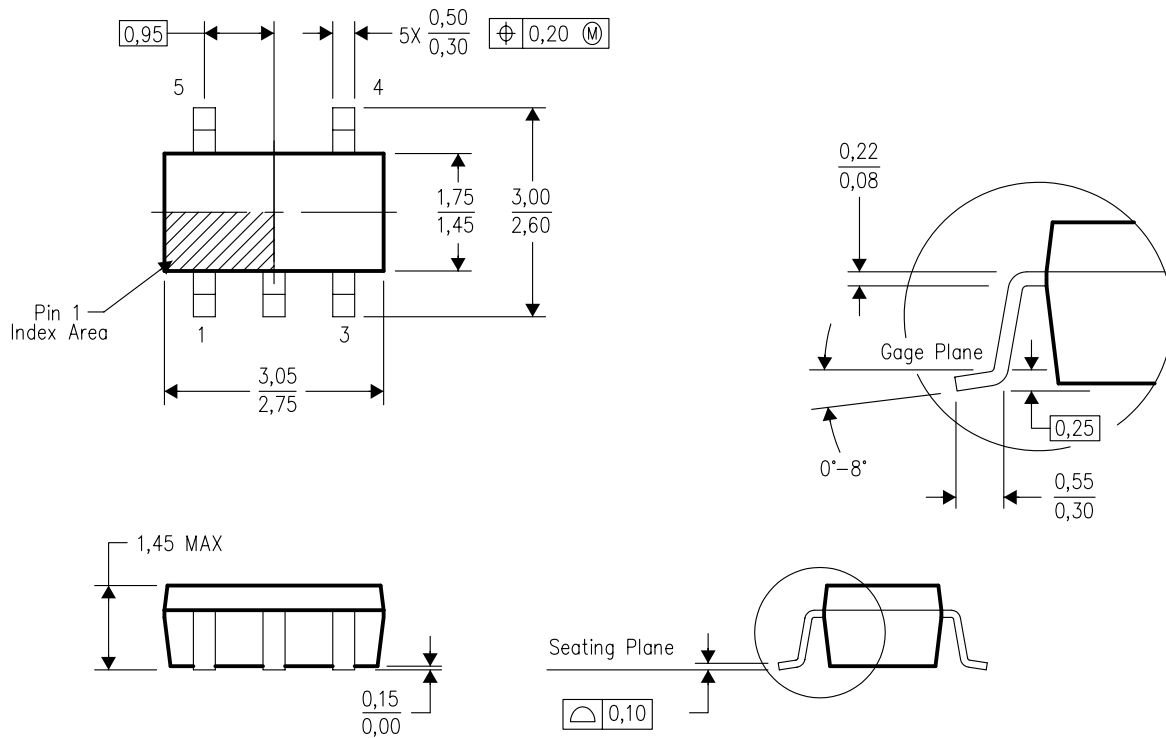


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM7341MF/NOPB	SOT-23	DBV	5	1000	203.0	190.0	41.0
LM7341MFE/NOPB	SOT-23	DBV	5	250	203.0	190.0	41.0
LM7341MFX/NOPB	SOT-23	DBV	5	3000	206.0	191.0	90.0

## DBV (R-PDSO-G5)

## PLASTIC SMALL-OUTLINE PACKAGE



4073253-4/K 03/2006

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-178 Variation AA.



DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - D. Publication IPC-7351 is recommended for alternate designs.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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